

1.6x0.6mm RIGHT ANGLE SMD CHIP LED **LAMP**

Part Number: KPA-1606SURCK

Hyper Red

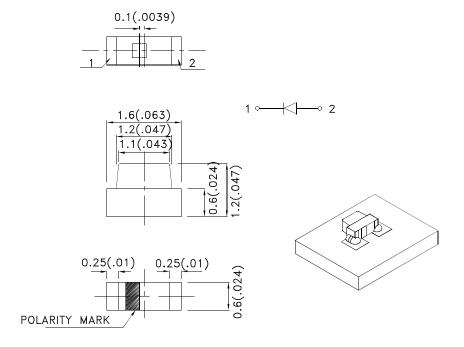
Features

- 1.6mmx0.6mm right angle SMT LED,1.2mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package :2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.





SPEC NO: DSAD2552 **REV NO: V.12** DATE: APR/30/2010 PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu DRAWN: XULINA** ERP: 1203000476

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
KPA-1606SURCK	Hyper Red (AlGaInP)	WATER CLEAR	110	250	110°

Notes

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
lR	Reverse Current	Hyper Red		10	uA	V _R =5V

Notes:

- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

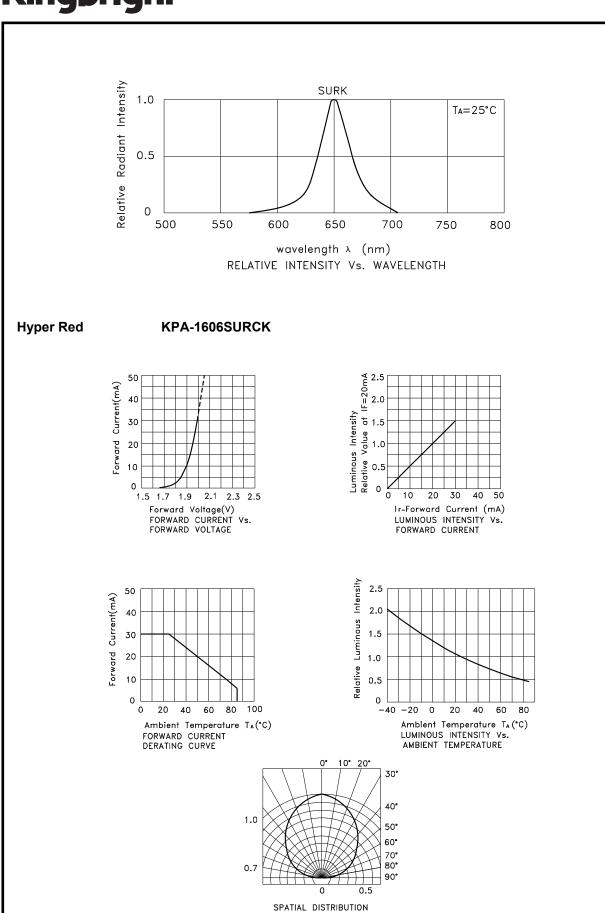
Parameter	Hyper Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	185	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

SPEC NO: DSAD2552 REV NO: V.12 DATE: APR/30/2010 PAGE: 2 OF 5

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: XULINA ERP: 1203000476



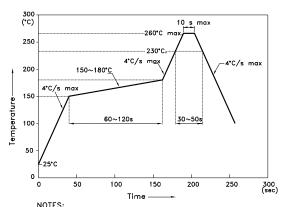
SPEC NO: DSAD2552 REV NO: V.12 DATE: APR/30/2010 PAGE: 3 OF 5

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: XULINA ERP: 1203000476

KPA-1606SURCK

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



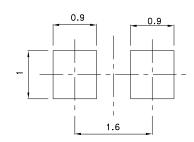
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

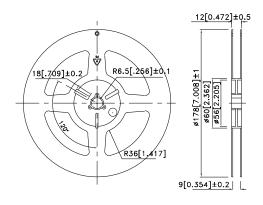
 3.Number of reflow process shall be 2 times or less.

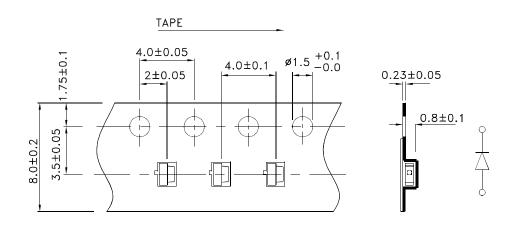
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



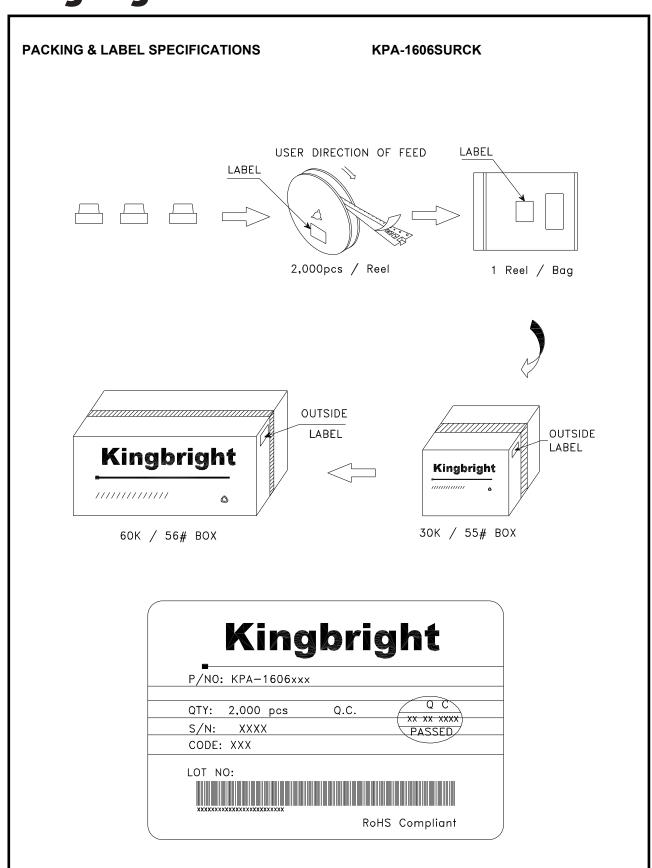
Tape Dimensions (Units : mm)

Reel Dimension





SPEC NO: DSAD2552 REV NO: V.12 DATE: APR/30/2010 PAGE: 4 OF 5
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: XULINA ERP: 1203000476



SPEC NO: DSAD2552 APPROVED: WYNEC REV NO: V.12 CHECKED: Allen Liu DATE: APR/30/2010 DRAWN: XULINA PAGE: 5 OF 5 ERP: 1203000476